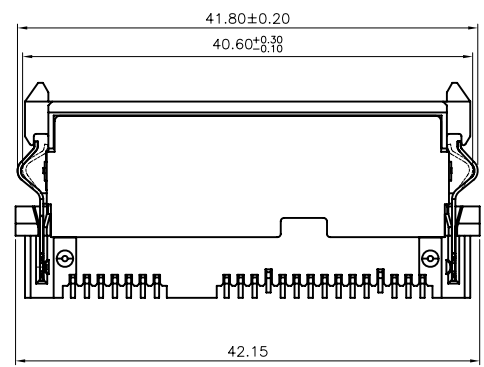
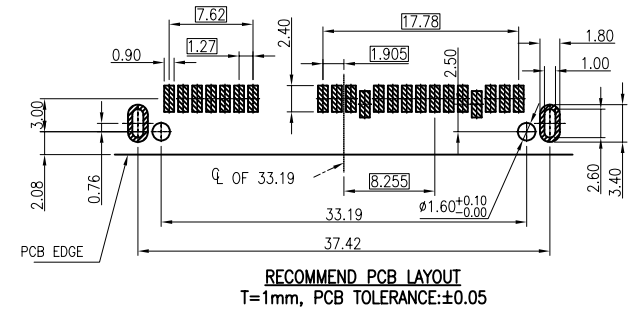
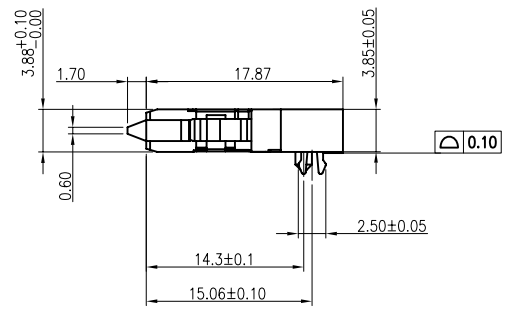
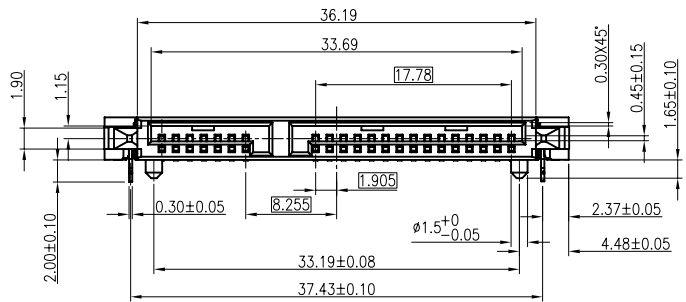
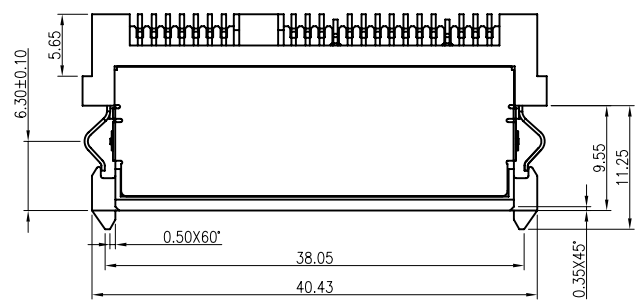


REV.	DESCRIPTION	DATE	DWN	APVD
A	RELEASED	28OCT11	Lee	WZ
A1		09NOV11	Lee	WZ

NOTE:  
 1. MATERIAL:  
 HOUSING: HIGH TEMPERATURE PLASTICS.  
 CONTACTS: COPPER ALLOY.  
 SPRING WITH BOARDLOCKS: STAINLESS STEEL SUS304-H.  
 SHELL: STAINLESS STEEL.  
 2. FINISH:  
 CONTACTS: (SEE TABLE) GOLD PLATED ON CONTACT AREA,  
 100μ" Min MATTE-TIN PLATING ON SOLDER TAIL,  
 WITH ENTIRE CONTACT UNDERPLATED 50μ" Min NICKEL.  
 BOARDLOCKS WITH SPRING: 30μ" Min NI-PI PLATED.  
 SHELL: 30μ" Min NI-PI PLATED



[15μ"]	09-0119-02
[G/F]	09-0119-01
MIN. GOLD THICKNESS	PART NUMBER

TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± - 1 PLC ± 0.3 2 PLC ± 0.2 3 PLC ± 0.15 4 PLC ± - ANGLES ± 3°	DWN Jackson_lee 09NOV2011 CHK CIYONG_JIANG 09NOV2011 APVD Wei_ZHANG 09NOV2011	<b>Zhongxiang Electron Science CO.,LTD</b>		
MATERIAL SEE NOTE	APPLICATION SPEC	NAME SATA 22P, RIGHT ANGLE SMT TYPE .		
FINISH SEE NOTE	WEIGHT 3.65 g	SIZE A3	DRAWING NO C-09-0119	RESTRICTED TO -
PROJECTION	DIMENSIONS: MM	CUSTOMER DRAWING	SCALE -	SHEET 1 OF 1 REV A1

8 7 6 5 4 3 2 1